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Term: L32 and (temperature sens\$3 or thermal\$2 sens\$3)

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<u>Set</u> <u>Name</u> <u>Query</u> side by side	<u>Hit</u> <u>Count</u>	<u>Set</u> <u>Name</u> result set
<i>DB=PGPB,USPT,USOC,EPAB,JPAB; PLUR=YES; OP=ADJ</i>		
<u>L34</u> 6679628[uref]	12	<u>L34</u>
<u>L33</u> L32 and (temperature sens\$3 or thermal\$2 sens\$3)	176	<u>L33</u>
<u>L32</u> L30 and (substrate or die or IC or integrated circuit or printed circuit or chip) L30 and (second substrate or second die or second chip or separate substrate or separate die or separate chip or second IC or separate IC or second integrated circuit or separate integrated circuit or second printed near circuit or separate printed near circuit)	451	<u>L32</u>
<u>L31</u>	18	<u>L31</u>
<u>L30</u> L24 and (dual diode or dual transistor or second diode or second transistor or identical diodes or identical transistors)	630	<u>L30</u>
<u>L29</u> L27 and (semiconductor or substrate or silicon substrate or chip or integrated circuit or IC)	201	<u>L29</u>
<u>L28</u> L27 and (semiconductor or substrate or silicon subdtrate or chip or integrated circuit or IC)	201	<u>L28</u>
<u>L27</u> L26 and (calibrati\$3 or offset or lineari\$4 or temperature near compensat\$3)	214	<u>L27</u>
<u>L26</u> L25 and (gain or amplifier or comparator)	300	<u>L26</u>
<u>L25</u> L24 and (band gap or bandgap)	373	<u>L25</u>

<u>L24</u> (374/170,171,172,173,178;702/130,99;327/512,513;257/467,470)! [CCLS]	4864	<u>L24</u>
<u>L23</u> (374/170,171,172,173;702/130,99;327/512,513;257/467,470)! [CCLS]	4613	<u>L23</u>
<i>DB=PGPB,USPT,USOC,EPAB,JPAB,DWPI,TDBD; PLUR=YES; OP=ADJ</i>		
<u>L22</u> L20 and (band gap)	30	<u>L22</u>
<u>L21</u> L20 and (bandgap)	19	<u>L21</u>
<u>L20</u> L19 and (temperature sensor)	846	<u>L20</u>
<u>L19</u> (substrate near temperature) and (silicon substrate)	13308	<u>L19</u>
<u>L18</u> (three terminal chip)	16	<u>L18</u>
<u>L17</u> L16 and (three terminal)	96	<u>L17</u>
<u>L16</u> 374/\$.ccls.	29795	<u>L16</u>
<u>L15</u> three terminal near integrated circuit	45	<u>L15</u>
<i>DB=USPT; PLUR=YES; OP=ADJ</i>		
<u>L14</u> L13 and (calibrat\$3)	1	<u>L14</u>
<u>L13</u> 6252209.pn.	1	<u>L13</u>
<u>L12</u> L10 and (terminal\$1)	1	<u>L12</u>
<u>L11</u> L10 and (output)	1	<u>L11</u>
<u>L10</u> 6055489.pn.	1	<u>L10</u>
<i>DB=PGPB; PLUR=YES; OP=ADJ</i>		
<u>L9</u> L8 and (terminals)	1	<u>L9</u>
<u>L8</u> 20050099752	1	<u>L8</u>
<i>DB=PGPB,USPT,USOC,EPAB,JPAB,DWPI,TDBD; PLUR=YES; OP=ADJ</i>		
<u>L7</u> L6 and (bandgap)	12	<u>L7</u>
<u>L6</u> semiconductor near temperature near sens\$3	611	<u>L6</u>
<u>L5</u> L3 and (chip or substrate or integrated circuit or IC)	99	<u>L5</u>
<u>L4</u> L3 and (bandgap)	1	<u>L4</u>
<u>L3</u> (thermocouple) near (semiconductor)	227	<u>L3</u>
<i>DB=USPT; PLUR=YES; OP=ADJ</i>		
<u>L2</u> L1 and (temperature sensor)	1	<u>L2</u>
<u>L1</u> 6055489.pn.	1	<u>L1</u>

END OF SEARCH HISTORY

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<u>L1</u> 6055489.pn.	1	<u>L1</u>

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